REMARKS

Claims 1 and 4-10 are pending in the application. Claims 1 and 4-10 stand rejected under 35 U.S.C. 102(b) as being anticipated by Juret et al (US 5,013,255). Claim 10 also stands rejected under 35 U.S.C. 102(b) as being anticipated by Yumibe et al (US 5,378,160)

By this amendment, claim 11 is canceled. Examiner is requested to enter this amendment to place the application in better condition for appeal.

Applicants again traverse the rejections of the claims.

In the office action of June 14, 2004, Examiner contends that FIG. 1 of Juret shows "a plurality of elongate conductor 32,34, and both ends of these conductors being formed in a hook shape". Examiner asserts that the limitation of "the conductors have hook shapes at both ends" is met by Juret. However, the present application has no such claim limitation. Claim 1 of the application is clearly drawn to an assembly for the solderless interconnection of parallel substrates, said assembly comprising elongate conductors having a 3-bend hook shape at both the first and second ends thereof to provide a spring force on both the first and second ends thereof. The fact that the conductors of the references have bends at both ends is not sufficient to anticipate the invention.

Juret, in FIG. 1, shows elongate conductors 32, 34 having a 2-bend hook at one end to provide a spring force, but the second end of the conductors is either straight or a single right-angle bend depending on how the assembly is to be soldered into the circuit card. FIG. 5 of Yumibe shows an elongate conductor having a 3-bend hook shape at one end to provide a spring force, but the other end has a simple 90-degree bend to form a solder pad for reflow soldering to a

circuit card. FIG. 10 and FIG. 11 of Yumibe illustrate elongate conductors having a total of seven bends that provide a spring force in the middle and have solder pads at both ends.

Clearly, neither Juret or Yumibe teach 3-bend hook shapes at both ends of the elongate conductors (6 bends total), nor do either provide spring forces at both ends of the conductors. Thus neither Juret or Yumibe anticipates the present invention. This is not at all surprising, since neither Juret or Yumibe (nor any of the other references cited in the previous office actions) is intended to perform the function of the present invention to provide solderless connections between substrate.

The applicants believe the application is now in condition for allowance. Reconsideration, allowance, and prompt passage to issue are respectfully requested.

Respectfully submitted,
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